

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Junichiro YOSHIOKA et al. :
Serial No. NEW : Attn: Application Branch
Filed November 23, 2001 : Attorney Docket No. 2001_1740

SEMICONDUCTOR WAFER HOLDER AND
ELECTROPLATING SYSTEM FOR PLATING
A SEMICONDUCTOR WAFER

(Rule 1.53(b) Continuation
of Serial No. 09/463,698,
Filed January 31, 2000)

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.



INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Pursuant to the provisions of 37 CFR 1.56, 1.97 and 1.98, Applicants request consideration of the references listed on attached form PTO-1449. A legible copy of each reference listed on the form PTO-1449 was previously cited by or submitted to the Patent Office in prior parent application Serial No. 09/463,698.

1a. ☒ This Information Disclosure Statement is submitted:

within three months of the filing date (or of entry into the National Stage) of the above-entitled application, **or**

before the mailing date of the first Office Action on the merits,

and thus no certification and/or fee is required.

1b. ☐ This Information Disclosure Statement is submitted

after the events of above paragraph 1a and prior to the mailing date of a final Office Action or a Notice of Allowance or an action which otherwise closes prosecution in the application, and thus:

(1) ☐ the certification of paragraph 2 below is provided, **or**

(2) ☐ the fee of \$180.00 specified in 37 CFR 1.17(p) is enclosed.

1c. ☐ This Information Disclosure Statement is submitted:

after the mailing date of a final Office Action or Notice of Allowance or action which otherwise closes prosecution in the application, and prior to payment of the issue fee, and thus:

the certification of paragraph 2 below is provided, and

the fee of \$180.00 specified in 37 CFR 1.17(p) is enclosed.

2. It is hereby certified

a. ☐ that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Statement, or

b. ☐ that no item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application and, to the knowledge of the person signing the certification after making reasonable inquiry, was known to any individual designated in §1.56(c) more than three months prior to the filing of the Statement.

3. ☐ Consideration of the following list of additional information (including any copending or abandoned U.S. application, prior uses and/or sales, etc.) is requested.

4. For each non-English language reference listed on the attached form PTO-1449, reference is made to:

- a. ☐ a full or partial English language translation submitted herewith,
 - b. ☐ a foreign patent office search report (in the English language) submitted herewith,
 - c. ☐ the concise explanation contained in the specification of the present application at page ,
 - d. ☐ the concise explanation set forth in the attached English language abstract,
 - e. ☐ the concise explanation set forth below or on a separate sheet attached to the reference:
5. ☐ A foreign patent office search report citing one or more of the references is enclosed.

Respectfully submitted,

Junichiro YOSHIOKA et al.

By 

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November 23, 2001

FORM PTO 3149 (modified)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICELIST OF REFERENCES CITED BY APPLICANT(S)
(Use several sheets if necessary)

Date Submitted to PTO: November 23, 2001

ATTY DOCKET NO.
2001_1740SERIAL NO.
NEWAPPLICANT
Junichiro YOSHIOKA et al.FILING DATE
November 23, 2001

GROUP

19971 U.S. PTO
09/990387
11/23/01

U.S. PATENT DOCUMENTS

| *EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
|----------------------|----|--------------------|---------|----------------|-------|----------|-------------------------------|
| | AA | 5,227,041 | 7-1993 | Brogden et al. | | | |
| | AB | 5,843,296 | 12-1998 | Greenspan | | | |
| | AC | | | | | | |
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FOREIGN PATENT DOCUMENTS

| | | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION YES NO |
|--|----|--------------------|---------|---------|-------|----------|-----------------------|
| | AJ | 11-2000096 | 7-27-96 | JP | | | Abstr. |
| | AK | 11-140694 | 5-25-99 | JP | | | Abstr. |
| | AL | 6-108285 | 4-19-94 | JP | | | Abstr. |
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OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

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| | AO | JOURNAL EBARA, Vol. 181 (1998-10), "Summary of the Plating Apparatus", pp. 42-49 (with English translation). |
| | AP | |
| | AQ | |

EXAMINER

DATE CONSIDERED